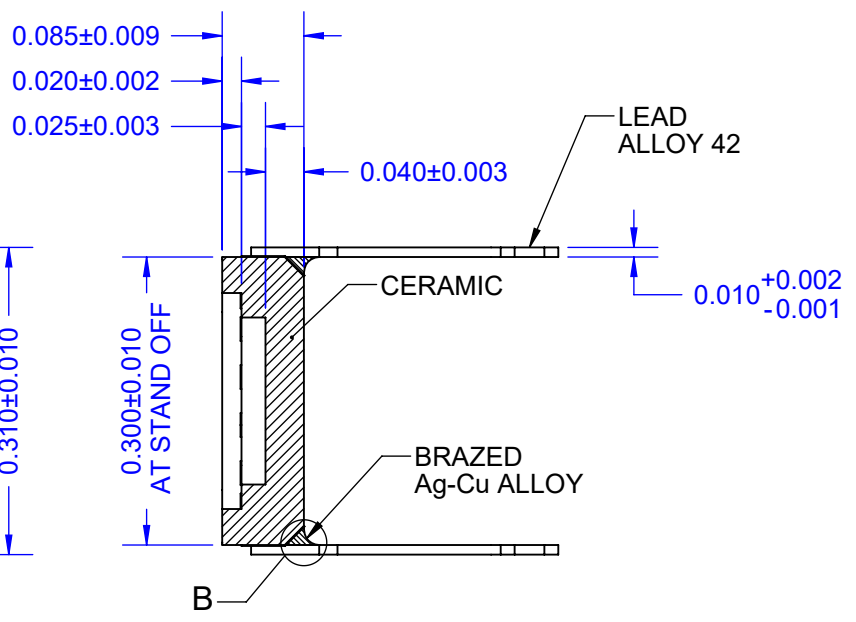
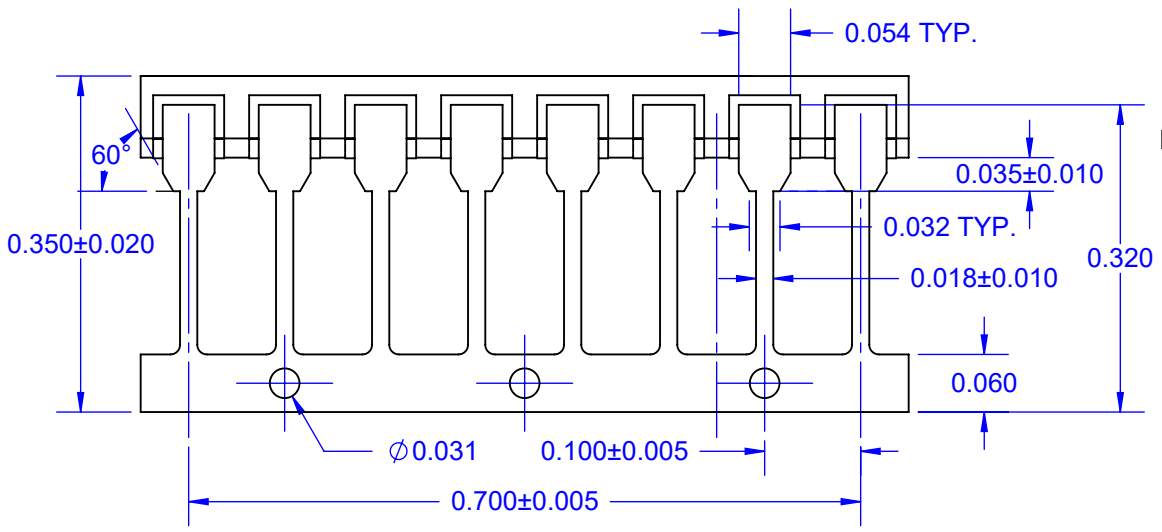


DIE PAD
0.174 x 0.244-inch
4.4 x 6.2mm



DETAIL B
SCALE 10 : 1

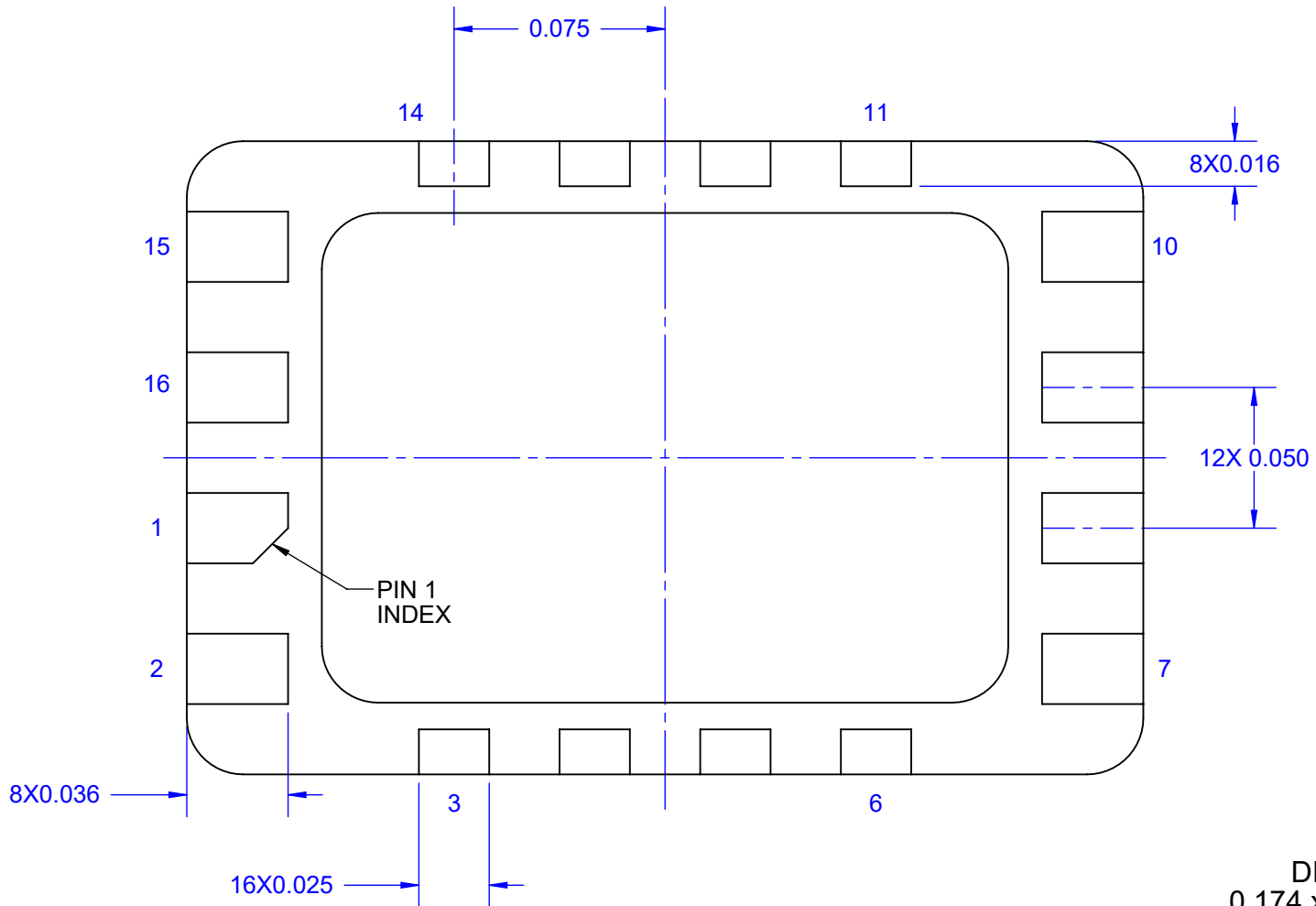


- NOTES: (Unless Otherwise Specified).
1. GOLD PLATE 60 micro-inch over 100 micro-inch (MIN) NICKEL.
 2. SEAL AREA TO BE METALLIZED.
 3. SEE PART NUMBER TABLE FOR DIE ATTACH METALLIZATION.
 4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
 5. LEAD RESISTANCE: 0.20 OHM MAX.
 6. TOLERANCE ± 0.005 -INCH UNLESS OTHERWISE SPECIFIED.
 7. CERAMIC (Al₂O₃ BLACK) SIDE-BRAZE PACKAGE KOVAR LEAD FRAME WITH GOLD METALLIZATION.

PART NUMBER TABLE		
PART NUMBER	DIE PAD	DWG
CERDIP16F3-N174x244	GOLD	167787

APPROVALS	DATE	TopLine®			
DRAWN T. Au	05/27/16				
ENG M. Hart	05/27/16	TITLE CERDIP16F3-N174x244 DIE PAD 4.4mm x 6.2mm			
MFG		SCALE	SIZE	DRAWING NO.	REV
QA		5:1	A	167787	A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 3
REVISED					

BONDING PADS

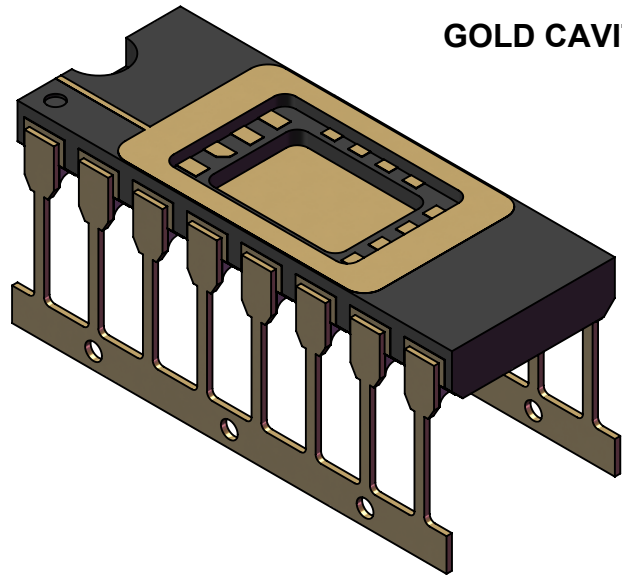


DIE PAD
0.174 x 0.244-inch
4.4 x 6.2mm

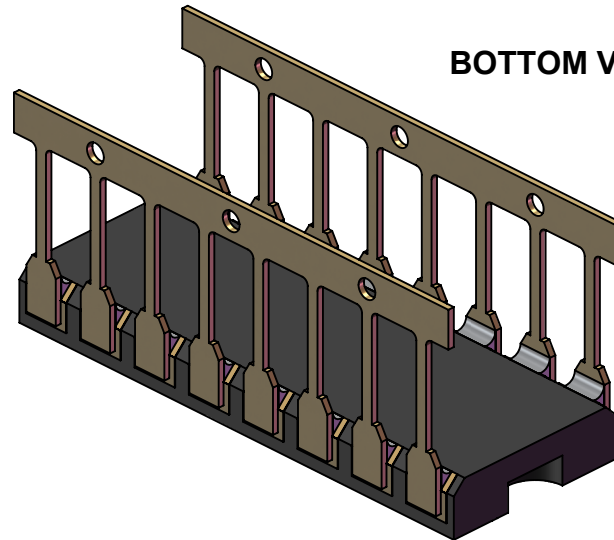
PART NUMBER TABLE		
PART NUMBER	DIE PAD	DWG
CERDIP16F3-N174x244	GOLD	167787

TopLine®			
TITLE CERDIP16F3-N174x244 DIE PAD 4.4mm x 6.2mm			
SCALE 5:1	SIZE A	DRAWING NO. 167787	REV A
DO NOT SCALE DRAWING			SHEET 2 OF 3

MODELS



GOLD CAVITY



BOTTOM VIEW

PART NUMBER TABLE		
PART NUMBER	DIE PAD	DWG
CERDIP16F3-N174x244	GOLD	167787

TopLine[®]			
TITLE		CERDIP16F3-N174x244 DIE PAD 4.4mm x 6.2mm	
SCALE	SIZE	DRAWING NO.	REV
5:1	A	167787	A
DO NOT SCALE DRAWING			SHEET 3 OF 3